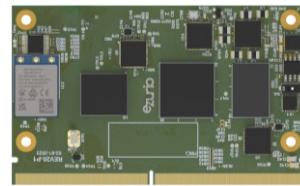


Secure, Smart, Standardized, and Connected IoT: Powerful NXP Edge Processing with Wi-Fi 6 or Wi-Fi 6E

Our customers asked for a high performance, robust SoM that simplifies their BOM, has reliable connectivity, uses a standard form factor, and is globally certified. One with multiple software options, a proven security architecture, long term software support, and security fixes.

Our new Nitrogen8M Plus SMARC is powered by **NXP's innovative i.MX 8M Plus** processor, NXP PMIC **PCA9450**, and our Sona Wi-Fi 6 or 6E and Bluetooth 5.4 wireless module families based on leading NXP and Infineon solutions, high performance LPDDR4 RAM, and eMMC storage. We combine this with our common SMARC carrier board; together they serve as a single board computer (SBC) that can speed your product to market. Alternately, work with us to create a custom carrier that fits your mechanical, environmental, temperature, and interface requirements.

- Powerful Heterogenous Multiprocessing:** Up to 1.8 GHz quad-core Cortex-A53 MPU and 800 MHz Cortex-M7 MCU allow you to run Linux and an RTOS on dedicated, hardware-firewalled subsystems.
- Dedicated Machine Learning:** High-performance edge machine learning via an integrated neural processing unit, up to 2.3 TOPS.
- Diverse Interfaces:** Multiple display, network, data, audio, camera.
- SMARC 2.2 Standard Form Factor:** 82mm x 50mm SMARC edge connector form factor which includes **onboard ethernet PHYs and a USB hub controller**. One design supports multiple processor, memory, and wireless configurations.
- Hardware Upgrade Roadmap:** Build a product design that can easily be upgraded to the latest processors and wireless options as future Ezurio based on the SMARC standard are released.
- Advanced Common Carrier/Development Board:** Display, camera, audio, Ethernet, USB, PCI-Express, CAN, I2C, SPI, UART, and more. Use in development, as an SBC equivalent in a product, or as reference designs for your carrier board design.



- Multiple options for Wi-Fi 6 or 6E (802.11ax) and Bluetooth 5.4**
 - Sona IF573 (**Infineon CYW55573**) tri-band Wi-Fi 6E and Bluetooth 5.4
 - Sona NX611 (**NXP IW611**) dual-band Wi-Fi 6 and Bluetooth 5.4
- Operating Temp:** Commercial (0° to +70 °C) / Industrial Rating (-40° to +85 °C)
- Multiple high performance memory options:**
 2GB LPDDR4 / 4GB LPDDR4 / 8GB LPDDR4 /
 16GB eMMC 16GB eMMC 16GB eMMC (MOQ required)
- Extensive range of pre-certified antennas** for optional Sona wireless modules
- US based manufacturing with Global Options:** Assembled in USA for local customer base and US market needs. Global manufacturing capability as part of Laird Connectivity footprint, growing reach to EMEA & APAC regions
- Diverse Software and BSP Options:** Choose from Yocto Linux / Buildroot Linux / Android / Zephyr RTOS / FreeRTOS (Cortex-M7)
- Secure and Encrypted Boot, Secure Enclave, and Secure File Storage:** Robust, secure, and optionally encrypted boot mechanism to ensure only trusted software boots on your device. Optionally store and use secure keys, certificates, and credentials in run-time isolated trusted environment.
- Power Efficient:** NXP PMIC, power optimized LPDDR4 and eMMC memory, core shut off, clock/voltage scaling, low power interfaces, power optimized single stream Wi-Fi mode enable highly optimized power consumption
- Long term hardware availability and software support:** Ezurio's products are specifically designed to meet the needs of the industrial and medical markets, which typically require 10 year or more product lifecycles. **Long-term software support** includes LTS Yocto Linux and Zephyr RTOS support with vulnerability remediation.

Key Features



Reliable Connectivity: Optional Wi-Fi 6/6E and BT5.3/5.4

Excellent Wi-Fi and BT Classic / LE connectivity in difficult environments, plus enterprise Wi-Fi support via WPA3-Enterprise for more secure and robust connections.



ML, Graphics, Video, Vision, and Audio – Up to 3 Displays

2.3 TOPS Machine Learning/Neural Processing Unit, up to 1200p60 or 4Kp30 displays, 2 shader GPU, 1080p60 multi codec encode and decode VPU, 2 MIPI-CSI camera interfaces, dedicated Image Signal Processing up to 12 MP, HiFi4 audio DSP



Secure Enclave and Secure Boot Powered by i.MX 8M Plus

Dedicated on-board security hardware, secure boot Linux, and high-performance and flexible secure storage system for passwords, certificates, and data storage.



Robust Software and Speed to Market

Choose from Yocto Linux, Buildroot Linux and Android for the Cortex-A53s; Zephyr RTOS, FreeRTOS for the Cortex-M7



Global Radio Approvals

Carries several modular FCC, IC, CE, UKCA, RCM, MIC, KC, and Bluetooth SIG approvals.

Personal Support from Design to Manufacture

Our industry-renowned support and field application engineering team is passionate about helping you speed your design to market.

Application Areas



Smart Buildings and Appliances



Touchscreens and Displays



Industrial IoT, Vision Systems



Food and Beverage



Medical Devices

Specifications

| Category | Feature | Specification |
|---------------------------------|--------------------------|---|
| Processors | Microprocessor | 4x Cortex®-A53 cores @ up to 1.8 GHz |
| | Microcontroller | 1x Cortex®-M7 core @ 800 MHz |
| | Audio | Tensilica® HiFi 4 DSP |
| | Graphics | GC7000UL with 2 shaders for 3D and GC520L for 2D |
| | Machine Learning | Neural Processing Unit (NPU) with 2.3 TOP/s |
| Memory | RAM | 2GB and 4GB, 8GB with qualifying MOQ. <i>(For custom sizes, please contact Sales)</i> |
| | Storage | 16GB. <i>(For custom sizes, please contact Sales)</i> |
| Machine Learning | Neural Processing Unit | <ul style="list-style-type: none"> Keyword detect, noise reduction, beamforming Speech recognition (i.e. Deep Speech 2) Image recognition (i.e. ResNet-50) |
| Graphics and Video | Graphics Processing Unit | <ul style="list-style-type: none"> 166 million triangles/sec 1.0 giga pixel/sec 16 GFLOPs 32-bit OpenGL ES 1.1, 2.0, 3.0, OpenCL 1.2, Vulkan 2D acceleration |
| | Video Processing Unit | <p>Video Decode</p> <ul style="list-style-type: none"> 1080p60 HEVC/H.265 Main, Main 10 (up to level 5.1) 1080p60 VP9 Profile 0, 2 1080p60 VP8 1080p60 AVC/H.264 Baseline, Main, High decoder <p>Video Encode</p> <ul style="list-style-type: none"> 1080p60 AVC/H.264 encoder 1080p60 HEVC/H.265 encoder |
| | Display Interfaces | <ul style="list-style-type: none"> 1x MIPI DSI, up to UWHD and WUXGA 1x LVDS Tx, up to 1920x1080p60 1x HDMI 2.0a Tx, up to 4kp30 |
| Vision | Camera | 1x 4-lane MIPI CSI, 1x 2-lane MIPI CSI |
| | Image Signal Processor | 375 Mpixel/s HDR ISP supporting configurations, such as 12MP@30fps, 4kp45, or 2x 1080p80 |
| Audio | Audio Interfaces | <ul style="list-style-type: none"> 2x I2S (Optionally 1 as HDA) eARC/ARC (HDMI) ASRC |
| Peripherals | Input/Output | <ul style="list-style-type: none"> 1x PCIe Gen3 1-Lane Dual Mode with PHY 2x USB 3.0/2.0 with PHY 2x USB 2.0 with PHY 2x Gbit Ethernet with IEEE® 1588, AVB (One also supports TSN) 2x CAN (Optionally CAN-FD on I-Temp) 3x UART 5 Mbit/s 5x I2C 2x SPI 1x SDIO 3.0/eMMC 5.1 14x GPIO |
| Optional Wireless Specification | Wi-Fi | Wi-Fi 6 or Wi-Fi 6E |
| | Frequency | Dual-Band 2.4GHz & 5GHz or Tri-Band 2.4GHz, 5GHz & 6GHz |
| | Bluetooth | Bluetooth 5.3 or Bluetooth 5.4 |
| Supply Voltage | | 5 V |
| Physical | Dimensions | SMARC 2.2 Standard - 82mm x 50mm |
| Environmental | Temp Range | 0°C to +70°C (Commercial) and -40° to +85 °C (Industrial) |
| Miscellaneous | Lead Free | Lead-free and RoHS-compliant |
| | Carrier Board | Carrier board, accessories, and evaluation software |
| Qualifications | Bluetooth® SIG | Bluetooth SIG Qualified Listing |
| Regulatory | Approvals | FCC/IC/CE/MIC/RCM |

For full specifications on the Nitrogen8M Plus SMARC, please see the appropriate datasheet.

Ordering Information

| Part | Description |
|--|--|
| N8MP_SMARC_SOM_2r16e | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 2GB / 16GB eMMC |
| N8MP_SMARC_SOM_2r16e_i | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 2GB / 16GB eMMC / -40 to +85°C |
| N8MP_SMARC_SOM_4r16e | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 4GB / 16GB eMMC |
| N8MP_SMARC_SOM_4r16e_i | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 4GB / 16GB eMMC / -40 to +85°C |
| N8MP_SMARC_SOM_8r16e | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 8GB / 16GB eMMC |
| N8MP_SMARC_SOM_8r16e_i | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 8GB / 16GB eMMC / -40 to +85°C |
| N8MP_SMARC_SOM_2r16e_NX611_1M | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 2GB / 16GB eMMC / NX611 |
| N8MP_SMARC_SOM_2r16e_NX611_1M_i | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 2GB / 16GB eMMC / NX611 / -40 to +85°C |
| N8MP_SMARC_SOM_4r16e_NX611_1M | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 4GB / 16GB eMMC / NX611 |
| N8MP_SMARC_SOM_4r16e_NX611_1M_i | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 4GB / 16GB eMMC / NX611 / -40 to +85°C |
| N8MP_SMARC_SOM_8r16e_NX611_1M | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 8GB / 16GB eMMC / NX611 |
| N8MP_SMARC_SOM_8r16e_NX611_1M_i | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 8GB / 16GB eMMC / NX611 / -40 to +85°C |
| N8MP_SMARC_SOM_2r16e_IF573_3M | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 2GB / 16GB eMMC / IF573 |
| N8MP_SMARC_SOM_2r16e_IF573_3M_i | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 2GB / 16GB eMMC / IF573 / -40 to +85°C |
| N8MP_SMARC_SOM_4r16e_IF573_3M | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 4GB / 16GB eMMC / IF573 |
| N8MP_SMARC_SOM_4r16e_IF573_3M_i | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 4GB / 16GB eMMC / IF573 / -40 to +85°C |

| Part | Description |
|---------------------------------|--|
| N8MP_SMARC_SOM_8r16e_IF573_3M | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 8GB / 16GB eMMC / IF573 |
| N8MP_SMARC_SOM_8r16e_IF573_3M_i | Nitrogen8M PLUS SMARC: i.MX8M Quad Plus / 8GB / 16GB eMMC / IF573 / -40 to +85°C |
| 450-00238 | Universal Heatsink for SMARC |
| SMARC_CAR | Universal Carrier Board Kit - Includes, antennas, power supply, DB9 cable |
| SMARC_CAR_BRD | Universal Carrier Board - Board Only (Note - SOM sold separately) |

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